

**REMARKS**

Claims 1 - 14 remain pending in the present application. By this Amendment, claim 1 has been amended to place the application in better condition for examination. Early examination and allowance of the application is respectfully requested.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "**Version with markings to show changes made.**"

In the event that this paper is not timely filed, Applicant respectfully petitions for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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Enclosures: Version with markings to show changes made



VERSION WITH MARKINGS TO SHOW CHANGES MADE 10/092,308

IN THE CLAIMS:

Claim 1 has been **AMENDED** to read as follows:

1. (Twice Amended) A method for fabricating a semiconductor device, comprising the steps of:

forming an overhanging structure having an umbrella-shaped portion on a semiconductor layer;

forming a protective film to cover a surface of said structure;

processing said protective film by removal so that an edge thereof on said semiconductor layer is positioned inside an edge of said umbrella-shaped portion;

depositing an electrode material on said semiconductor layer using umbrella-shaped portion as a mask; and

processing said electrode material to form an electrode at an interval from [and] the edge of said protective film,

wherein the protective film is apart from an edge of the electrode over the semiconductor layer.

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